PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Chyi HARN	11/18/2009
Sophia WANG	11/18/2009
Chun-Hung LIN	11/18/2009
Hsien-Wei CHEN	11/23/2009
Ming-Yen CHIU	11/23/2009

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12619460

CORRESPONDENCE DATA

Fax Number: (214)200-0853
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 214-651-5000
Email: eppsl@haynesboone.com
Correspondent Name: HAYNES AND BOONE, LLP IP Section
Address Line 1: 2323 Victory Avenue
Address Line 2: Suite 700
Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.1324

NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=1324_assignment#page1.tif source=1324_assignment#page2.tif source=1324_assignment#page3.tif	

Docket No.: 2009-0310 / 24061.1324
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Yu-Chyi Harn of No. 10, Lane 286, Sec. 2, Shuang-Yuan Road, Shuang-Xi Village
Bao-Shan, Hsin-Chu County, Taiwan, R.O.C.

(2) Sophia Wang of No. 25, Ze-Fan Road
Xin-Zhu City, Taiwan, R.O.C.

(3) Chun-Hung Lin of 5F, No. 112, Zhongpu 2nd Street
Taoyuan City, Taoyuan County 330, Taiwan, R.O.C.

(4) Hsien-Wei Chen of No. 57, Sueitang Street
Sinying City, Tainan County 730, Taiwan, R.O.C.

(5) Ming-Yen Chiu of 7F, No. 74, Lane 476, Sec. 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C.

have invented certain improvements in

DESIGN STRUCTURE FOR INTEGRATED CIRCUIT ALIGNMENT

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
xx filed on November 16, 2009 and assigned application number 12/619,460

and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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1. Inventor Name: Yu-Chyi Harn

Residence Address: No. 10, Lane 286, Sec. 2, Shuang-Yuan Road, Shuang-Xi Village
Bao-Shan, Hsin-Chu County, Taiwan, R.O.C.

Dated: 11/18/09

Inventor Signature

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2. Inventor Name: Sophia Wang

Residence Address: No. 25, Ze-Fan Road
Xin-Zhu City, Taiwan, R.O.C.

Dated: 11/18/09

Sophia Wang
Inventor Signature

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3. Inventor Name: Chun-Hung Lin

Residence Address: 5F, No. 112, Zhongpu 2nd Street
Taoyuan City, Taoyuan County 330, Taiwan, R.O.C.

Dated: C.H.Lin

11/18/09
Inventor Signature

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4. Inventor Name: Hsien-Wei Chen

Residence Address: No. 57, Sueitang Street
Sinying City, Tainan County 730, Taiwan, R.O.C.

Dated: 11, 23, 2009

Hsien-Wei Chen
Inventor Signature

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5. Inventor Name: Ming-Yen Chiu

Residence Address: 7F, No. 74, Lane 476, Sec. 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 11, 23, 2009

Ming-Yen Chiu
Inventor Signature
